# **ON Semiconductor**

# Is Now



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# MOSFET - Power, N-Channel, SUPERFET<sup>®</sup> III, FAST 650 V, 125 mΩ, 24 A

# NTPF125N65S3H

## Description

SUPERFET III MOSFET is ON Semiconductor's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This advanced technology is tailored to minimize conduction loss, provides superior switching performance, and withstand extreme dv/dt rate.

Consequently, SUPERFET III FAST MOSFET series helps minimize various power systems and improve system efficiency.

#### **Features**

- $700 \text{ V} @ \text{T}_{\text{J}} = 150^{\circ}\text{C}$
- Typ.  $R_{DS(on)} = 108 \text{ m}\Omega$
- Ultra Low Gate Charge (Typ. Q<sub>g</sub> = 44 nC)
- Low Effective Output Capacitance (Typ. C<sub>oss(eff.)</sub> = 379 pF)
- 100% Avalanche Tested
- These Devices are Pb-Free and are RoHS Compliant

## **Applications**

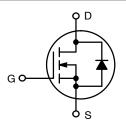
- Computing / Display Power Supplies
- Telecom / Server Power Supplies
- Industrial Power Supplies
- Lighting / Charger / Adapter

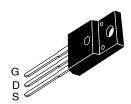


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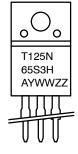
V <sub>DSS</sub>	R <sub>DS(ON)</sub> MAX	I <sub>D</sub> MAX
650 V	125 mΩ @ 10 V	24 A





TO-220 FULLPAK CASE 221D

## **MARKING DIAGRAM**



T125N65S3H = Specific Device Code

A = Assembly Location

′ = Year

WW = Work Week
ZZ = Lot Code

### **ORDERING INFORMATION**

See detailed ordering and shipping information on page 2 of this data sheet.

## **ABSOLUTE MAXIMUM RATINGS** ( $T_C = 25^{\circ}C$ , Unless otherwise noted)

Symbol	Parameter	Value	Unit	
V <sub>DSS</sub>	Drain to Source Voltage		650	V
$V_{GSS}$	Gate to Source Voltage DC		±30	V
		AC (f > 1 Hz)	±30	V
I <sub>D</sub>	Drain Current	Continuous (T <sub>C</sub> = 25°C)	24*	Α
		Continuous (T <sub>C</sub> = 100°C)	15*	
I <sub>DM</sub>	Drain Current	Drain Current Pulsed (Note 1)		Α
E <sub>AS</sub>	Single Pulsed Avalanche Energy (Note 2)		216	mJ
I <sub>AS</sub>	Avalanche Current (Note 2)		4.7	Α
E <sub>AR</sub>	Repetitive Avalanche Energy (Note 1)		1.71	mJ
dv/dt	MOSFET dv/dt Peak Diode Recovery dv/dt (Note 3)		120	V/ns
			20	
$P_{D}$	Power Dissipation	(T <sub>C</sub> = 25°C)	37	W
		Derate Above 25°C	0.30	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range		-55 to +150	°C
$T_L$	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 s		260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.
\*Drain current limited by maximum junction temperature.

## THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
$R_{ heta JC}$	Thermal Resistance, Junction to Case, Max.	3.37	°C/W
$R_{ heta JA}$	R <sub>0JA</sub> Thermal Resistance, Junction to Ambient, Max.		

## PACKAGE MARKING AND ORDERING INFORMATION

Part Number	Top Marking	Package	Shipping
NTPF125N65S3H	T125N65S3H	TO-220 FULLPAK	50 Units / Tube

<sup>1.</sup> Repetitive rating: pulse-width limited by maximum junction temperature. 2.  $I_{AS} = 4.7 \text{ A}$ ,  $R_G = 25 \Omega$ , starting  $T_J = 25^{\circ}\text{C}$ . 3.  $I_{SD} \le 12 \text{ A}$ ,  $\text{di/dt} \le 200 \text{ A/}\mu\text{s}$ ,  $V_{DD} \le 400 \text{ V}$ , starting  $T_J = 25^{\circ}\text{C}$ .

# **ELECTRICAL CHARACTERISTICS** (T<sub>C</sub> = 25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
OFF CHARACT	ERISTICS		•	•		•
$BV_{DSS}$	Drain to Source Breakdown Voltage	$V_{GS} = 0 \text{ V, } I_D = 1 \text{ mA, } T_J = 25^{\circ}\text{C}$	650			V
		V <sub>GS</sub> = 0 V, I <sub>D</sub> = 1 mA, T <sub>J</sub> = 150°C	700			V
$\Delta BV_{DSS}/\Delta T_{J}$	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 10 mA, Referenced to 25°C		0.63		V/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 650 V, V <sub>GS</sub> = 0 V			1	μΑ
		V <sub>DS</sub> = 520 V, T <sub>C</sub> = 125°C		1.3		
I <sub>GSS</sub>	Gate to Body Leakage Current	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA
ON CHARACTE	RISTICS			•		•
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{GS} = V_{DS}$ , $I_D = 2.1 \text{ mA}$	2.4		4.0	V
R <sub>DS(on)</sub>	Static Drain to Source On Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 12 A		108	125	mΩ
9FS	Forward Transconductance	V <sub>DS</sub> = 20 V, I <sub>D</sub> = 12 A		26		S
DYNAMIC CHA	RACTERISTICS		I	1		
C <sub>iss</sub>	Input Capacitance	$V_{DS} = 400 \text{ V}, V_{GS} = 0 \text{ V}, f = 250 \text{ kHz}$		2200		pF
C <sub>oss</sub>	Output Capacitance			34		pF
C <sub>oss(eff.)</sub>	Effective Output Capacitance	V <sub>DS</sub> = 0 V to 400 V, V <sub>GS</sub> = 0 V		379		pF
C <sub>oss(er.)</sub>	Energy Related Output Capacitance	V <sub>DS</sub> = 0 V to 400 V, V <sub>GS</sub> = 0 V		56		pF
Q <sub>g(tot)</sub>	Total Gate Charge at 10 V			44		nC
Q <sub>gs</sub>	Gate to Source Gate Charge	$V_{DS} = 400 \text{ V}, I_D = 12 \text{ A}, V_{GS} = 10 \text{ V}$ (Note 4)		11		nC
Q <sub>gd</sub>	Gate to Drain "Miller" Charge	(14616-4)		12		nC
ESR	Equivalent Series Resistance	f = 1 MHz		1.1		Ω
WITCHING CH	IARACTERISTICS			•		•
t <sub>d(on)</sub>	Turn-On Delay Time			22		ns
t <sub>r</sub>	Turn-On Rise Time	$V_{DD} = 400 \text{ V}, I_D = 12 \text{ A},$		9.2		ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{GS} = 10 \text{ V, R}_{g} = 7.5 \Omega$ (Note 4)		66		ns
t <sub>f</sub>	Turn-Off Fall Time	, ,		2.3		ns
SOURCE-DRAI	N DIODE CHARACTERISTICS		ı			
I <sub>S</sub>	Maximum Continuous Source to Drain Diode Forward Current				24	Α
I <sub>SM</sub>	Maximum Pulsed Source to Drain Diode Forward Current				67	Α
V <sub>SD</sub>	Source to Drain Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 12 A			1.2	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>DD</sub> = 400 V, I <sub>SD</sub> = 12 A,		314		ns
Q <sub>rr</sub>	Reverse Recovery Charge	$dI_F/dt = 100 \text{ A}/\mu \text{s}$		4.5		μС

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Essentially independent of operating temperature typical characteristics.

## TYPICAL CHARACTERISTICS (T<sub>C</sub> = 25°C unless otherwise noted)

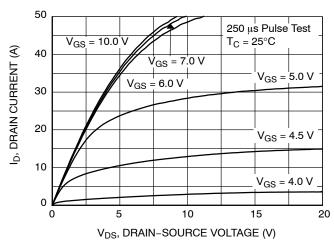


Figure 1. On-Region Characteristics

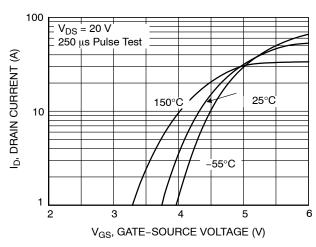


Figure 2. Transfer Characteristics

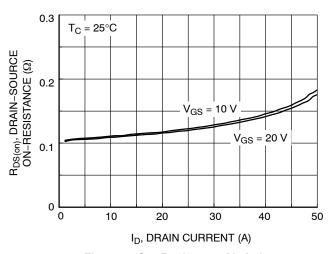


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

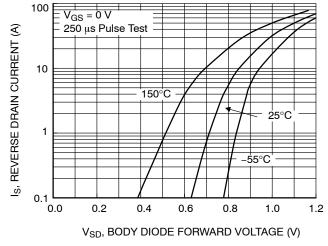


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

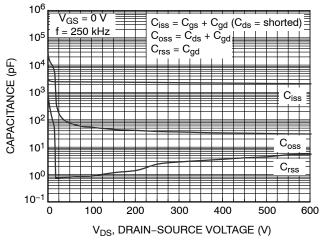


Figure 5. Capacitance Characteristics

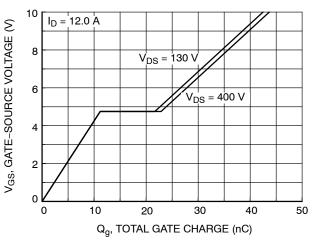


Figure 6. Gate Charge Characteristics

## TYPICAL CHARACTERISTICS (T<sub>C</sub> = 25°C unless otherwise noted) (continued)

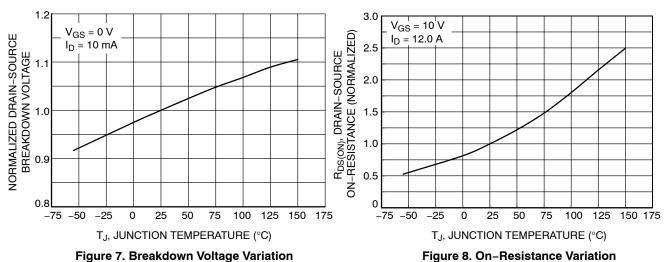


Figure 7. Breakdown Voltage Variation vs. Temperature

100

vs. Temperature 30 25 20 15 10

Figure 10. Maximum Drain Current vs. Case **Temperature** 

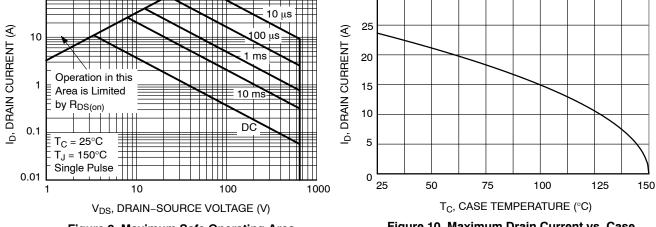


Figure 9. Maximum Safe Operating Area

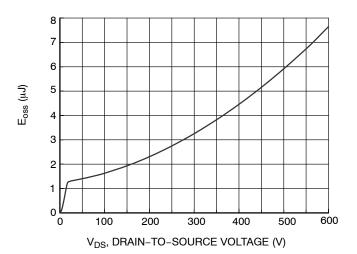


Figure 11. E<sub>OSS</sub> vs. Drain to Source Voltage

## **TYPICAL CHARACTERISTICS** ( $T_C = 25^{\circ}C$ unless otherwise noted) (continued)

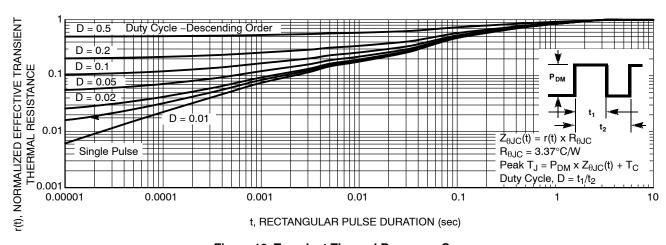


Figure 12. Transient Thermal Response Curve

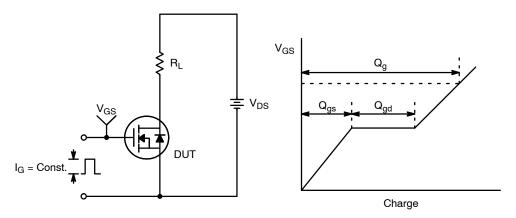


Figure 13. Gate Charge Test Circuit & Waveform

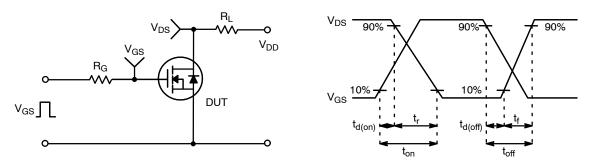


Figure 14. Resistive Switching Test Circuit & Waveforms

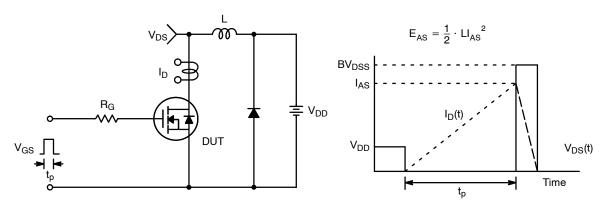


Figure 15. Unclamped Inductive Switching Test Circuit & Waveforms

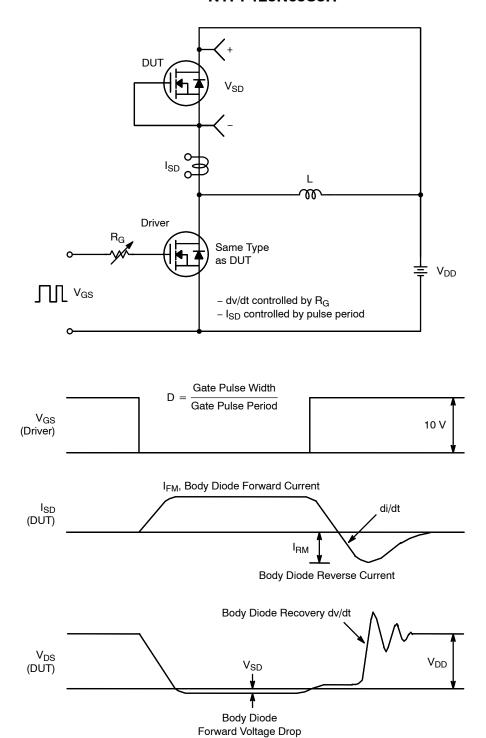


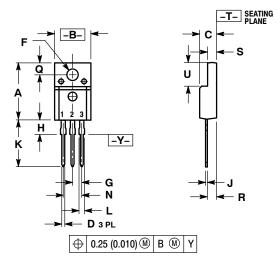
Figure 16. Peak Diode Recovery dv/dt Test Circuit & Waveforms

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#### PACKAGE DIMENSIONS

#### TO-220 FULLPAK

CASE 221D-03 ISSUE K



#### NOTES

- DIMENSIONING AND TOLERANCING PER ANSI
  Y14 5M 1982
- 2. CONTROLLING DIMENSION: INCH
- 221D-01 THRU 221D-02 OBSOLETE, NEW STANDARD 221D-03.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.617	0.635	15.67	16.12
В	0.392	0.419	9.96	10.63
C	0.177	0.193	4.50	4.90
D	0.024	0.039	0.60	1.00
F	0.116	0.129	2.95	3.28
G	0.100 BSC		2.54 BSC	
Н	0.118	0.135	3.00	3.43
7	0.018	0.025	0.45	0.63
K	0.503	0.541	12.78	13.73
L	0.048	0.058	1.23	1.47
N	0.200 BSC		5.08	BSC
Q	0.122	0.138	3.10	3.50
R	0.099	0.117	2.51	2.96
S	0.092	0.113	2.34	2.87
0	0.239	0.271	6.06	6.88

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